

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Appl. No.	: 10/809,182	Confirmation No. 6820
Applicant(s)	: UMENO, Kuniharu et al.	
Filed	: 03/25/2004	
TC/A.U.	: 1712	
Examiner	: Robert E. Sellers	
Title	: Resin Composition for Encapsulating Semiconductor Chip and Semiconductor Device Therewith	
Docket No.	: 033036.076	
Customer No.	: 25461	

**MAIL STOP RCE**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450  
Sir:

**AMENDMENT ACCOMPANYING RCE**

Please amend the above-identified application as follows:

**Amendments to the specification** are reflected beginning on page 2.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 4 of this paper.

**Remarks/Arguments** begin on page 9 of this paper.

**Attachments:**

Corrected Declaration – 4 pgs.  
Certified Translations of JP 2003-083937 and 2003-083938  
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